

## Desoldering Applications



### Wire Wrap Pins

Desolder pins for easy removal. Removes solder buildup. Eliminates potential intermittent problems.



### Lugs/Posts

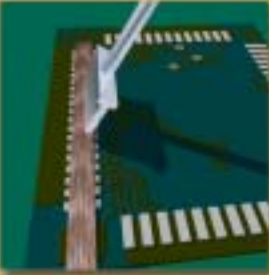
Wicks solder completely, eliminating solder splash or drip. Leaves terminal fluxed and ready for resoldering.



### Components

Easily removes solder from components with straight or clinched leads. Minimum heat required. No damage to board or components.

## Cleaning Applications



### SMT Pads

Quickly and safely desolders entire rows of SMT pads. Applications-specific sizes desolder individual fine-pitch SMT pads.



### BGA Pads

Safely removes solder from BGA pads and chips in three to four passes. Completely removes all residual solder and facilitates chip repositioning.



### Solder Bridges

Completely removes solder bridges. Eliminates potential shorts. No damage to boards or circuitry.



### Clean Script

Selectively retouches etched script. Improves aesthetic appearance. Eliminates secondary identification. Easy to use.



### Blobs

Eliminates and removes blobs as well as shorts and icicles. Leaves circuitry smooth. Cleans potential problem areas.



### Finger Connectors

Cleans finger connectors and surface mount pads.

## Braid Sizes

BGA Purple



.030"/0.8mm White



.060"/1.5mm Yellow



.080"/2.0mm Green



.110"/2.8mm Blue



.145"/3.7mm Brown



.210"/5.3mm Red



# Chem-Wik® Desoldering Braid

## Chem-Wik® Desoldering Braid

As the standard desoldering braid for service and repair, Chem-Wik® Desoldering Braid ensures fast and safe desoldering. The ultra-pure, oxygen free copper braid quickly and completely removes solder from circuit boards and components. Its fast wicking action protects components from harmful heat damage. PermaPak™ Barrier Packaging ensures ultimate braid freshness and speed by sealing out harmful effects of the environment and protecting against oxidation.

### Chem-Wik® Desoldering Braid:

Meets or exceeds the greatest range of performance standards:

- MIL-F-14256F Type R
- NASA STD-8739.3 Soldered Electrical Connections
- ANSI/IPC J STD-004, Type ROLO

### Static Dissipative Packaging:

- DOD Standard 1686C and MIL-HDBK-263B
- Mil-Std-2000A
- Mil-B-81705C Static Decay Rate Provision

## Chem-Wik® Rosin

The fast, safe rosin flux desoldering braid for removing solder from leads and components

- Coated with ultra high purity rosin
- Quickly and thoroughly removes solder
- Noncorrosive Type R rosin flux

## Chem-Wik® Rosin SD

The fast, safe rosin flux desoldering braid packaged in static dissipative bobbins

- Reduces the risk of damage associated with static electricity
- Coated with noncorrosive ultra high purity Type R rosin flux
- Quickly and thoroughly removes solder



PermaPak™ Barrier Packaging contains 25 bobbins per package

## Chem-Wik® Product Selection Guide

| PRODUCT            | COLOR  | SIZE        | 5'<br>1.5m | 25'<br>7.5m | 50'<br>15.0m | 100'<br>30.5m | 500'<br>152.5m | APPLICATION    |
|--------------------|--------|-------------|------------|-------------|--------------|---------------|----------------|----------------|
| Chem-Wik® Rosin    | Gray   | .030"/0.8mm |            | 2-25L       | 2-50L        | 2-100L        | 2-500L         | Micro-Circuits |
|                    | Yellow | .050"/1.3mm |            | 5-25L       | 5-50L        | 5-100L        | 5-500L         | Small Pads     |
|                    | Green  | .075"/1.9mm |            | 7-25L       | 7-50L        | 7-100L        | 7-500L         | Medium Pads    |
|                    | Blue   | .100"/2.5mm |            | 10-25L      | 10-50L       | 10-100L       | 10-500L        | Large Pads     |
| Chem-Wik® Rosin SD | Gray   | .030"/0.8mm | 2-5L       |             |              |               |                | Micro-Circuits |
|                    | Yellow | .050"/1.3mm | 5-5L       |             |              |               |                | Small Pads     |
|                    | Green  | .075"/1.9mm | 7-5L       |             |              |               |                | Medium Pads    |
|                    | Blue   | .100"/2.5mm | 10-5L      |             |              |               |                | Large Pads     |

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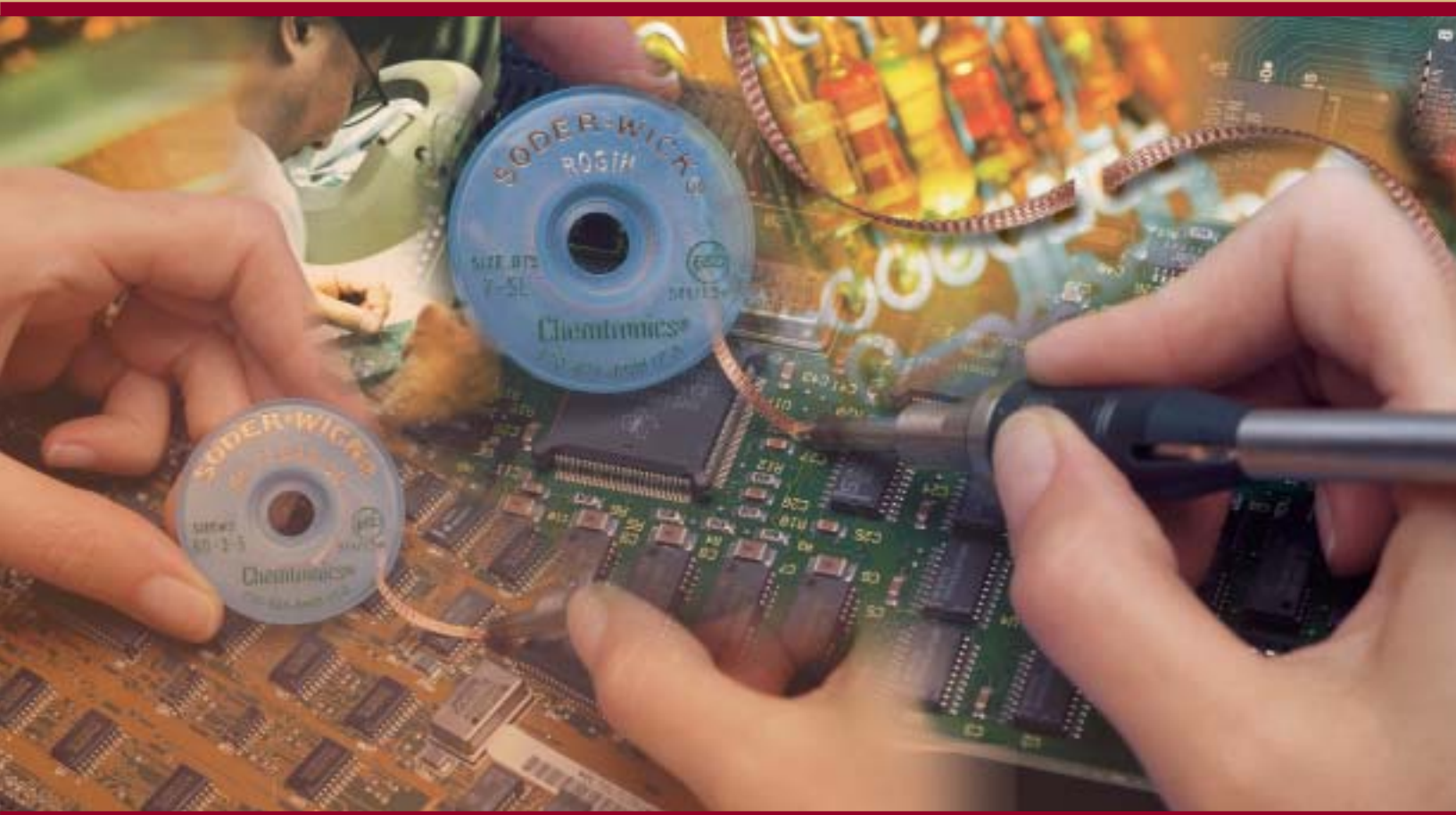


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SW CAT 0010.02 Rev. 0506 5M



## The Leader in Desoldering Technology

# Soder-Wick® — World’s Leading Brand of Desoldering Braid

Soder-Wick®, the world's leading brand of desoldering braid, is the fastest, cleanest and safest braid in the industry.

It significantly reduces rework/repair time and minimizes the risk of heat damage to the board. Its geometrically precise weave design allows for maximum capillary action and solder capacity. Soder-Wick® Desoldering Braid optimizes heat transfer through the braid and into the solder joint, resulting in faster wicking action than any other competitive brand. Minimal flux residue on the board speeds up the cleaning process, or eliminates it entirely.

Soder-Wick® Desoldering Braid is available in the most comprehensive variety of widths, lengths and flux types.

Application-specific sizes allow for precision solder removal in a flash. Sealed in Performance Pak™ Barrier Packaging and VacuPak™ Vacuum Sealed Packaging, Soder-Wick® Desoldering Braid is completely protected from the harmful effects of the environment. The VacuPak™ vacuum-sealed can guarantees the braid to be as fast and fresh as the day it was made. The can serves as a protective storage container once the pack has been opened and is also easily stacked on the shelf. Its superior packaging provides predictable quality and performance, time and time again.

Soder-Wick® Desoldering Braid meets or exceeds the greatest range of qualitative and performance standards:

- MIL-F-14256 F type R flux
- NASA-STD-8739.3 Soldered Electrical Connections
- DOD-STD-883E, Method 2022
- ANSI/IPC J STD-004, Type ROLO

Static Dissipative Packaging:

- Qualifies under MIL-STD-1686C and MIL-HDBK-263B as a non-ESD generator
- Meets the Static Decay Rate Provision of MIL-B-81705C and MIL-STD-2000A

Soder-Wick® No Clean SD:

- Meets MIL-STD-883B, Bellcore TR-NWT-000078, ANSI/IPC J SF-818
- Meets parameters tested by the Singapore Institute of Standards and Industrial Research (SISIR) for Solderability
- ANSI/IPC J STD-004, Type ROLO

All 5' and 10' bobbins are offered on static dissipative bobbins, and only Soder-Wick® static dissipative bobbins are labeled by heat stamping. This eliminates paper labels that increase the risk of ESD damage. Competitive desoldering braid does not offer this increased level of protection.



Soder-Wick® Lead-Free SD

The fastest, safest desoldering braid formulated specifically for use with lead-free applications

- Engineered specifically for high temperature, lead-free solders
- Transfers heat to the solder joint more quickly and efficiently than conventional desoldering braids
- Specifically designed for all lead-free solders
- Can also be used with Tin/Lead solders
- Packaged in ESD-safe static dissipative bobbins
- Minimizes the risk of damage associated with static electricity
- Noncorrosive ultra high purity no-clean flux
- Will not leave ionic contamination on the boards
- Especially effective at removing residual solder from SMT pads
- RoHS compliant

Soder-Wick® BGA

The most effective, economical way to safely and completely remove solder from BGA pads and chips

- Sized and designed specifically for BGA pad and chip rework/repair
- Entire BGA pads cleaned in three to four passes
- Available in rosin and no-clean fluxes
- Packaged in ESD-safe static dissipative bobbins

Soder-Wick® Rosin

The fastest, safest rosin flux desoldering braid for removing solder from printed circuit boards

- Noncorrosive ultra high purity Type R rosin flux
- Minimizes the risk of heat damage to the board
- Will not leave ionic contamination on the boards

Soder-Wick® Rosin SD

The fastest, safest rosin flux desoldering braid packaged in static dissipative bobbins

- Soder-Wick® Rosin packaged in ESD-safe static dissipative bobbins
- Minimizes the risk of damage associated with static electricity
- Noncorrosive ultra high purity Type R rosin flux
- Minimizes the risk of heat damage to the board
- Will not leave ionic contamination on the boards

Soder-Wick® No Clean SD

The fastest, cleanest no-clean flux desoldering braid packaged in static dissipative bobbins

- Soder-Wick® No Clean packaged in ESD-safe static dissipative bobbins
- Minimizes the risk of damage associated with static electricity
- Patented noncorrosive, halide free, organic no-clean flux
- Desolders up to 40% faster than competitive no-clean braids and leaves boards cleaner
- Meets Bellcore TR-NWT-000078 and ANSI IPC SF-818 for Surface Insulation Resistance

## Soder-Wick® Product Selection Guide

| PRODUCT                  | SIZE | COLOR       | 5'<br>1.5m | 10'<br>3.0m | 25'<br>7.5m | 100'<br>30.5m | 500'<br>152.5m | VACUPAK™ | APPLICATION         |
|--------------------------|------|-------------|------------|-------------|-------------|---------------|----------------|----------|---------------------|
| Soder-Wick® Lead-Free SD | 2    | .060"/1.5mm | Yellow     | 40-2-5      | 40-2-10     |               |                | SW14025  | Small Pads, SMDs    |
|                          | 3    | .080"/2.0mm | Green      | 40-3-5      | 40-3-10     |               |                | SW14035  | Medium Pads         |
|                          | 4    | .110"/2.8mm | Blue       | 40-4-5      | 40-4-10     |               |                | SW14045  | Large Pads          |
| Soder-Wick® BGA Rosin    | BGA  |             | Purple     | 80-BGA-5    |             |               |                | SW180BGA | BGA Pads and Chips  |
| Soder-Wick® BGA No Clean | BGA  |             | Purple     | 60-BGA-5    |             |               |                | SW160BGA | BGA Pads and Chips  |
| Soder-Wick® Rosin        | 1    | .030"/0.8mm | White      |             | 50-1-25     |               |                |          | SMD, Micro-Circuits |
|                          | 2    | .060"/1.5mm | Yellow     |             | 50-2-25     | 50-2-100      | 50-2-500       |          | Small Pads, SMDs    |
|                          | 3    | .080"/2.0mm | Green      |             | 50-3-25     | 50-3-100      | 50-3-500       |          | Medium Pads         |
|                          | 4    | .110"/2.8mm | Blue       |             | 50-4-25     | 50-4-100      | 50-4-500       |          | Large Pads          |
|                          | 5    | .145"/3.7mm | Brown      |             | 50-5-25     |               |                |          | Terminals           |
|                          | 6    | .210"/5.3mm | Red        |             | 50-6-25     |               |                |          | Large Lugs          |
| Soder-Wick® Rosin SD     | 1    | .030"/0.8mm | White      | 80-1-5      | 80-1-10     |               |                | SW18015  | SMD, Micro-Circuits |
|                          | 2    | .060"/1.5mm | Yellow     | 80-2-5      | 80-2-10     |               |                | SW18025  | Small Pads, SMDs    |
|                          | 3    | .080"/2.0mm | Green      | 80-3-5      | 80-3-10     |               |                | SW18035  | Medium Pads         |
|                          | 4    | .110"/2.8mm | Blue       | 80-4-5      | 80-4-10     |               |                | SW18045  | Large Pads          |
|                          | 5    | .145"/3.7mm | Brown      | 80-5-5      | 80-5-10     |               |                | SW18055  | Terminals           |
|                          | 6    | .210"/5.3mm | Red        | 80-6-5      |             |               |                |          | Large Lugs          |
| Soder-Wick® No Clean SD  | 1    | .030"/0.8mm | White      | 60-1-5      | 60-1-10     |               |                | SW16015  | SMD, Micro-Circuits |
|                          | 2    | .060"/1.5mm | Yellow     | 60-2-5      | 60-2-10     |               |                | SW16025  | Small Pads, SMDs    |
|                          | 3    | .080"/2.0mm | Green      | 60-3-5      | 60-3-10     |               |                | SW16035  | Medium Pads         |
|                          | 4    | .110"/2.8mm | Blue       | 60-4-5      | 60-4-10     |               |                | SW16045  | Large Pads          |
|                          | 5    | .145"/3.7mm | Brown      | 60-5-5      | 60-5-10     |               |                | SW16055  | Terminals           |
|                          | 6    | .210"/5.3mm | Red        | 60-6-5      |             |               |                |          | Large Lugs          |
| Soder-Wick® Unfluxed     | 2    | .060"/1.5mm | Yellow     |             | 70-2-25     |               |                |          | Small Pads, SMDs    |
|                          | 3    | .080"/2.0mm | Green      |             | 70-3-25     |               |                |          | Medium Pads         |
| Soder-Wick® Unfluxed SD  | 2    | .060"/1.5mm | Yellow     |             | 75-2-10     |               |                |          | Small Pads, SMDs    |
|                          | 3    | .080"/2.0mm | Green      |             | 75-3-10     |               |                |          | Medium Pads         |
|                          | 4    | .110"/2.8mm | Blue       |             | 75-4-10     |               |                |          | Large Pads          |

All 5' and 10' Soder-Wick® Desoldering Braid is offered on static dissipative bobbins. Performance Pak™ Barrier Packaging contains 25 bobbins per package.



**VacuPak™ Vacuum Sealed Packaging**  
Guarantees Soder-Wick® Desoldering Braid to be as fast and fresh as the day it was made. The VacuPak™ can contains 10 bobbins with 5 feet of braid on each bobbin.



Fastest, Cleanest and Safest Braid in the Industry  
www.chemtronics.com